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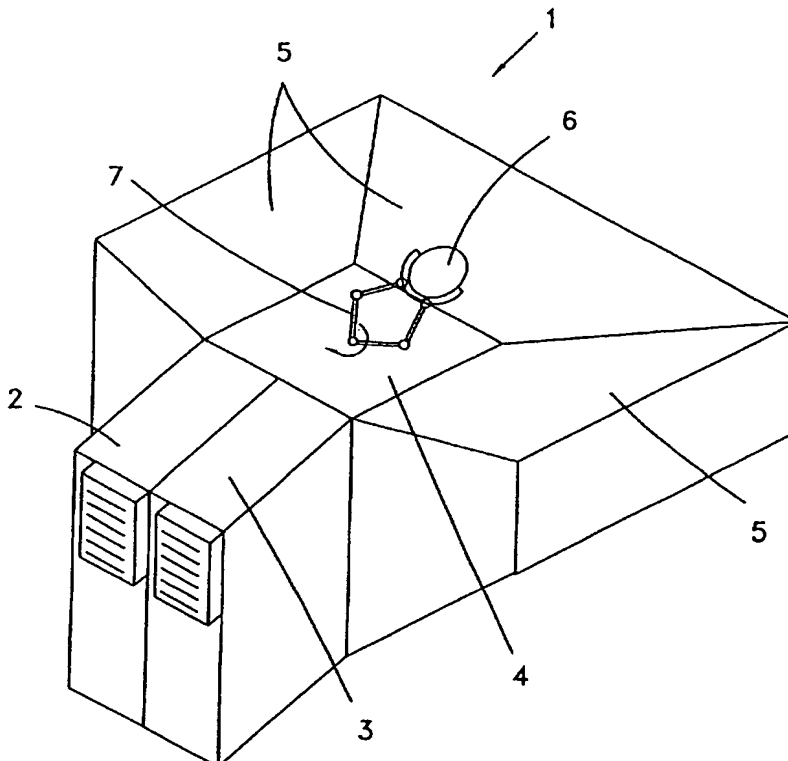
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(54) Title: DEVICE AND SYSTEM FOR RECORDING THE MOTION OF A WAFER AND A METHOD THEREFORE



(57) Abstract: The invention provides a device that can be used to record the motion of a wafer and fine perturbations and vibrations in its motion during its progress through and between semiconductor process and inspection machines in the course of the actual manufacturing process or during a test cycle of the processing or inspection machine. It also provides a system and a method which uses this record to detect, locate, and identify any mechanical malfunction of the processing or inspection machine which has caused, or could cause, defects in the manufactured wafer whether directly or indirectly.

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